



ICTP 2020

CALL FOR ABSTRACTS

Extended Abstract Submission Date:
AUGUST 31, 2019

The 13th International Conference on the Technology of Plasticity (ICTP 2020)

July 26-31, 2020 • The Ohio State University
Ohio Union • Columbus, Ohio, USA



From fundamental science to industrial application, the breadth of the metal forming community will convene at The 13th International Conference on the Technology of Plasticity (ICTP 2020). Scientists and engineers from across industry, academia, and government will share their latest improvements and innovations in all aspects of metal forming science and technology, with the intent of facilitating linkages and collaborations among these groups.

DON'T MISS THIS OPPORTUNITY TO LEARN FROM AND CONNECT WITH LEADERS IN METAL FORMING..

This conference will provide a forum for presentations and discussions on all areas related to the plastic deformation of materials to create components. Topics of particular interest include, but are not limited to:

- Metal Forming Processes & Equipment
- Joining by Forming and Deformation
- Microstructure and Damage Development & Characterization
- Big Data and Metal Forming
- High Speed and Impulse Forming
- Agile Metal Forming
- Microstructure Development by Forming
- Technologies to Speed Innovation
- Value of, and Limits to, Simulation

Learn more about technical topics planned for this congress at
www.tms.org/ICTP2020.

CONFERENCE ORGANIZERS:

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SUBMIT YOUR ASBTRACT BY AUGUST 31, 2019 AT:
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